

Technical Datasheet

Tradename: VD90.5101 / VD90.5105 / VD90.5106 / VD90.5108 /
VD90.5109 / VD90.5110 / VD90.5115 - MARTIN Solder Balls lead free
Issue: October 2020
Reference: TDS solder balls Sn96.5Ag3Cu0.5_e.doc

1. Identification

Material: Sn96,5Ag3Cu0,5
Form and Dimension: Spheres Ø 0,2 – 1,0 mm ±0,01mm

2. Composition

Element	Control Limit
Sn	Balance
Ag	3,0 – 4,0 %
Cu	0,4 – 0,6 %

Deoxidizing Melting Process, Purity of the components minimum 99,99%

3. Impurities (DIN EN 29453:1993)

Element	Control Limit (%)
Fe	<0,0015
Ni	<0,0006
Zn	<0,0006
As	<0,0008
Cd	<0,005
Sb	<0,003
Pb	<0,05
Bi	<0,02

Analysenmethode: RFA – Röntgen Fluoreszenz Analyse

4. Physikalische Eigenschaften

Melting point-/Range: 217 - 220°C
Specific Gravity: 7,37 g/cm³
Thermal conductivity: 60 W/(m*K)
Young's Modulus: ~ 16,6 KPa

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